

**IN THE ABSTRACT:**

Please amend the Abstract of the Disclosure as follows.

(no Fig.)

~~The invention refers to a~~ A method as well as a bonding installation for machining of wood workpieces. At least one machining aggregate is provided where in the supplying and discharge region one conveying system each is arranged. Besides machining of the front end region by ~~means of~~ the machining aggregate also other machinings are carried out on the wood workpiece.